

SOT1024-2

plastic low profile fine-pitch ball grid array package; 169 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA169
Package type industry code	LFBGA169
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	7-8-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1.04	-	1.17	1.3	mm
A ₂	package height	0.85	-	0.91	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	169	-	



2. Package outline

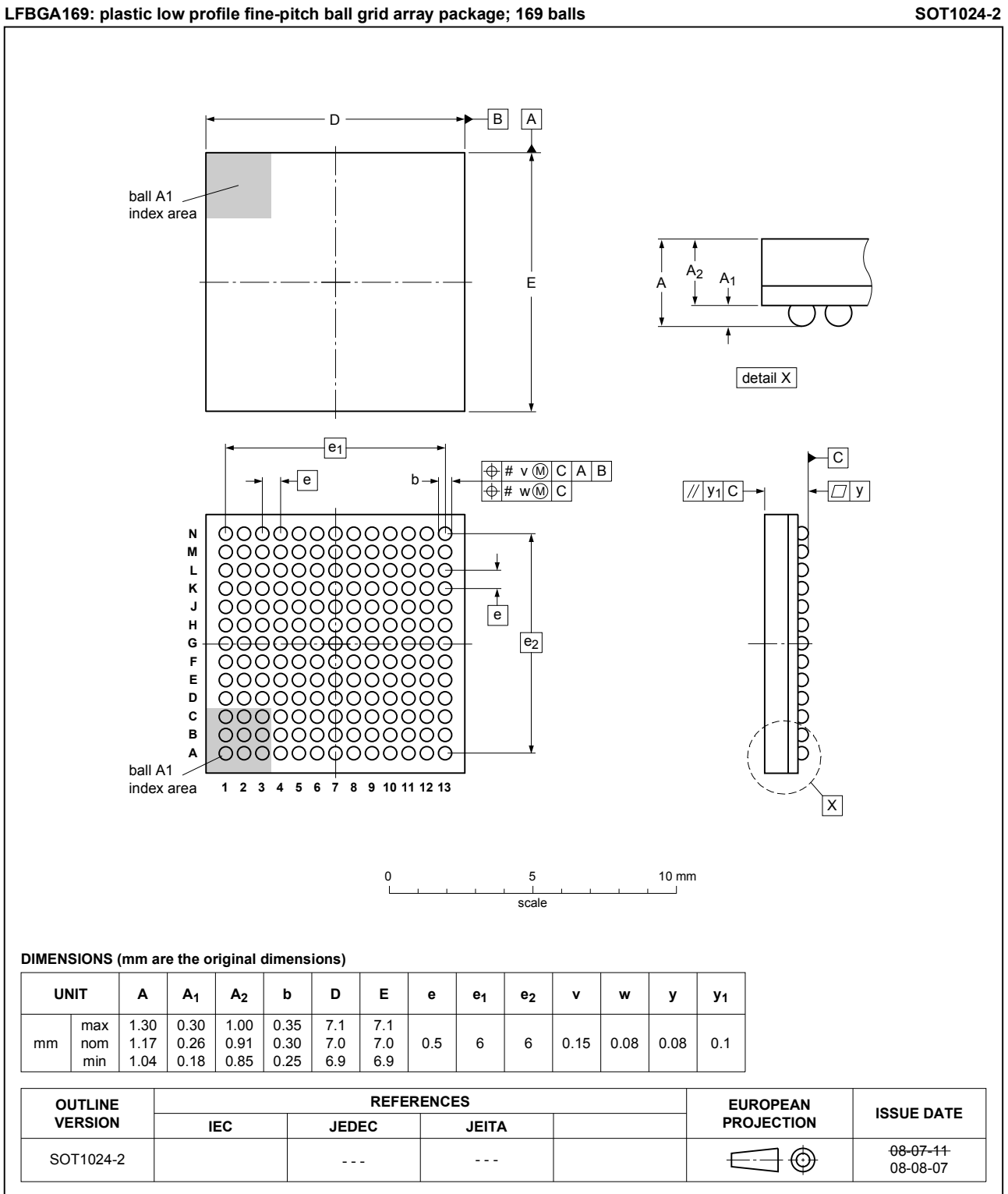


Fig. 1. Package outline LFBGA169 (SOT1024-2)

3. Soldering

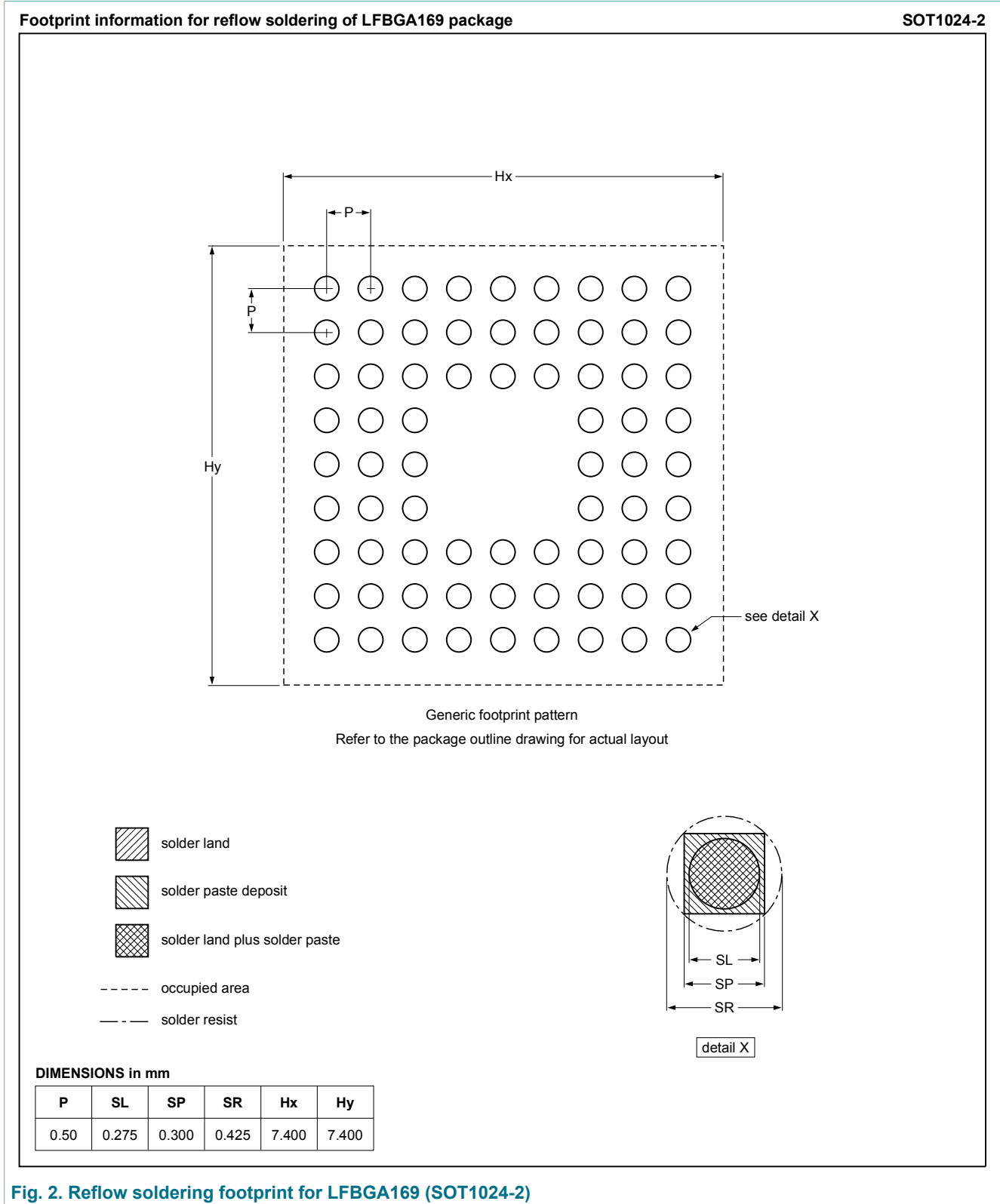


Fig. 2. Reflow soldering footprint for LFBGA169 (SOT1024-2)

4. Legal information

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